



VMDSEMI

**VUSC1P2R280PA**

**Datasheet**



VMDSEMI

## General Description

## Symbol

$V_{(BR)DSS}$	$R_{DS(ON)_{max}}$	$I_D$
-12V	28mΩ@-4.5V	-6A
	32mΩ@-3.7V	
	40mΩ@-2.5V	
	63mΩ@-1.8V	
	150mΩ@-1.5V	

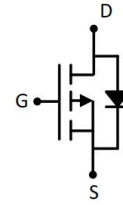


Figure 1 Symbol of VUSC1P2R280PA

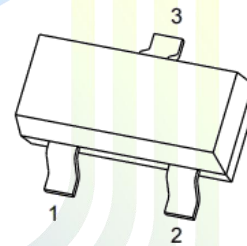
## Features

- Trench FET Power MOSFET
- Excellent  $R_{DS(on)}$  and Low Gate Charge

## Application

- DC/DC Converter
- Load Switch for Portable Devices
- Battery Switch

## Package Type



1. GATE
2. SOURCE
3. DRAIN

## SOT-23-3L

Figure 2 Package Type of VUSC1P2R280PA

## Ordering Information

Product Name	Package
VUSC1P2R280PA	SOT-23-3L

**Absolute Maximum Ratings** ( $T_A = 25\text{ }^\circ\text{C}$ , unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DSS}$	-12	V
Gate-Source Voltage	$V_{GSS}$	$\pm 8$	V
Continuous Drain Current <sup>Note1</sup>	$I_D$	-6	A
Pulsed Drain Current <sup>Note2</sup>	$I_{DM}$	-20	
Total Power Dissipation <sup>Note4</sup>	$P_D$	0.4	W
Junction Temperature	$T_J$	150	$^\circ\text{C}$
Storage Temperature	$T_{STG}$	-55 to 150	$^\circ\text{C}$

**Thermal Resistance**

Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Ambient <sup>Note5</sup>	$R_{\theta JA}$		312.5		$^\circ\text{C}/\text{W}$



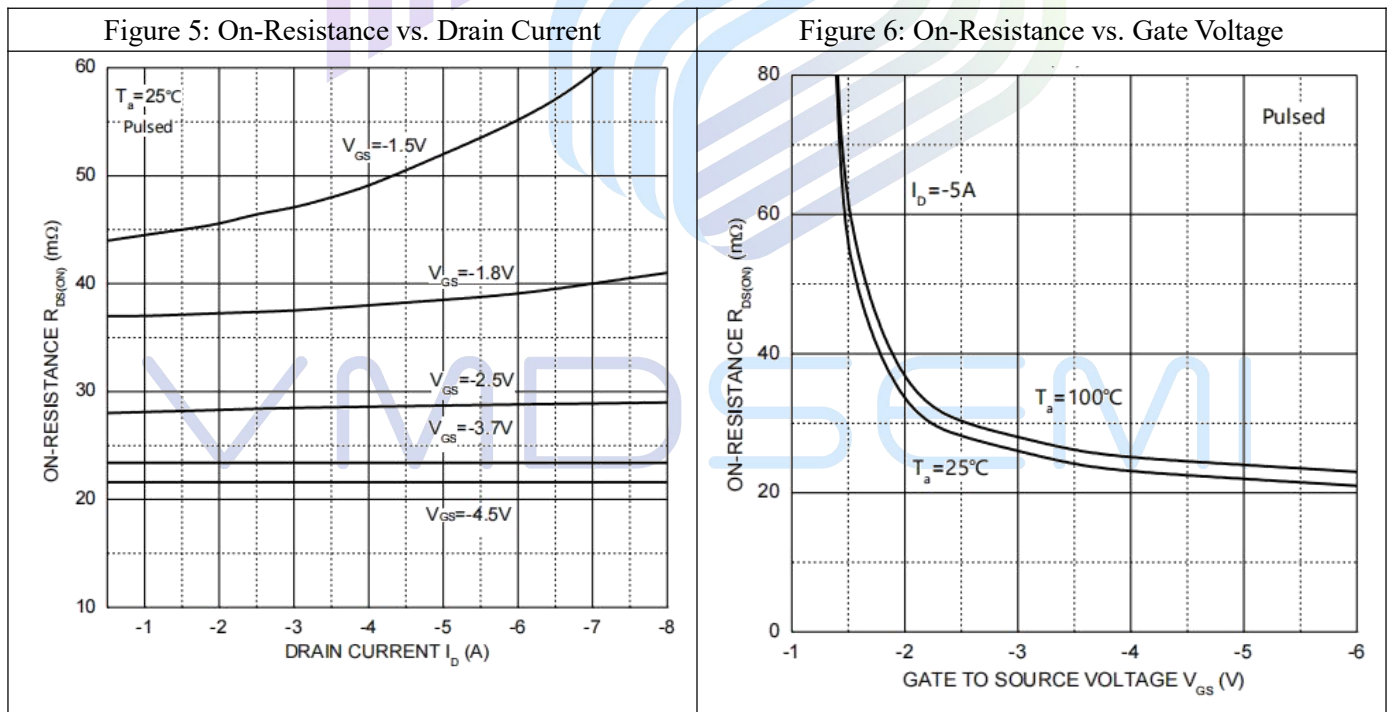
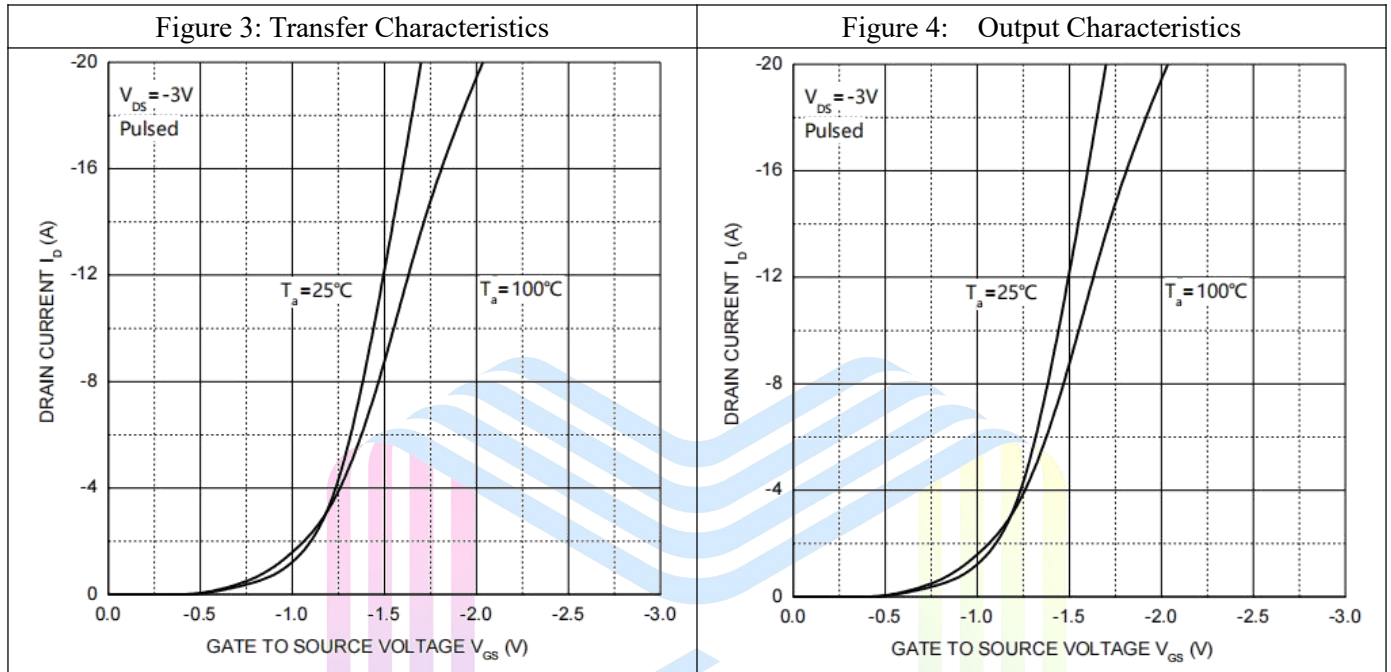
**Electrical Characteristics** ( $T_A = 25\text{ }^\circ\text{C}$ , unless otherwise specified)

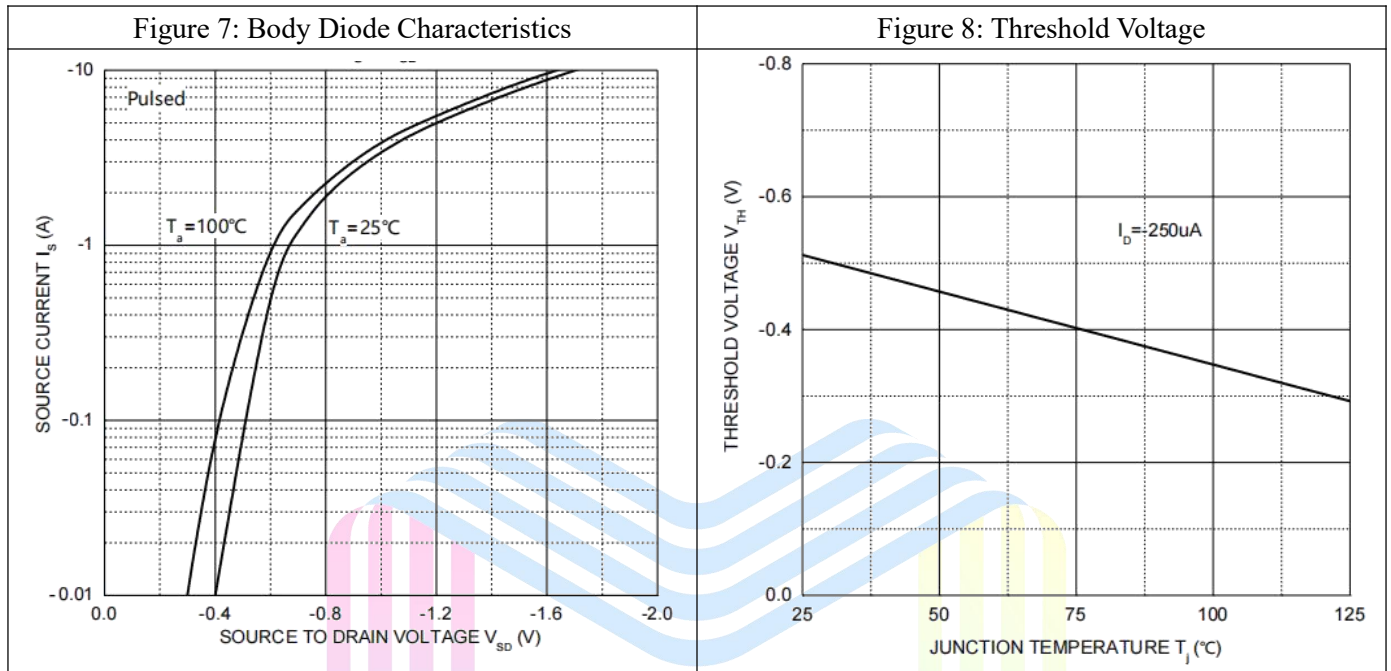
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Statistic Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	-12			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=-12V, V_{GS}=0V$			-1	$\mu A$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS}=\pm 8V, V_{DS}=0V$			$\pm 0.1$	$\mu A$
Gate Threshold Voltage <sup>Note3</sup>	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-0.4	-0.65	-1	V
Static Drain-Source On-Resistance <sup>Note3</sup>	$R_{DS(on)}$	$V_{GS}=-4.5V, I_D=-5A$		19	28	mΩ
		$V_{GS}=-3.7V, I_D=-4.6A$		21	32	
		$V_{GS}=-2.5V, I_D=-4.3A$		27	40	
		$V_{GS}=-1.8V, I_D=-1A$		35	63	
		$V_{GS}=-1.5V, I_D=-0.5A$		50	150	
Forward Transconductance <sup>Note3</sup>	$g_{FS}$	$V_{DS}=-5V, I_D=-5A$	10	14		S
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{ISS}$	$V_{DS}=-6V$		1275		pF
Output Capacitance	$C_{OSS}$	$V_{GS}=0V$		255		pF
Reverse Transfer Capacitance	$C_{RSS}$	$f=1MHz$		236		pF
Total Gate Charge	$Q_g$	$V_{DS}=-6V$		14		nC
Gate-Source Charge	$Q_{gs}$	$V_{GS}=-4.5V$		2.3		
Gate-Drain Charge	$Q_{gd}$	$I_D=-5A$		3.6		
Gate Resistance	$R_g$	$f=1MHz, \text{Open drain}$	1.9		19	Ω
<b>Switching Parameters</b>						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=-6V$		26		ns
Turn-on Rise Time	$t_r$	$V_{GS}=-4.5V$		24		
Turn-off Delay Time	$t_{d(off)}$	$R_L=6\Omega$		45		
Turn-off Fall Time	$t_f$	$R_G=1\Omega, I_D=-4A$		20		
<b>Diode Characteristics</b>						
Diode Forward Voltage <sup>Note3</sup>	$V_{DS}$	$V_{GS}=0V, I_S=-4A$			-1.2	V
Continuous Source Current	$I_S$	$T_C=25\text{ }^\circ\text{C}$			-6	A
Pulsed Source Current	$I_{SM}$				-20	
Diode Reverse Recovery Time	$t_{rr}$	$I_F=-4A$		24	48	ns
Diode Reverse Recovery Charge	$Q_{rr}$	$dI/dt=100A/\mu s$		8	16	nC

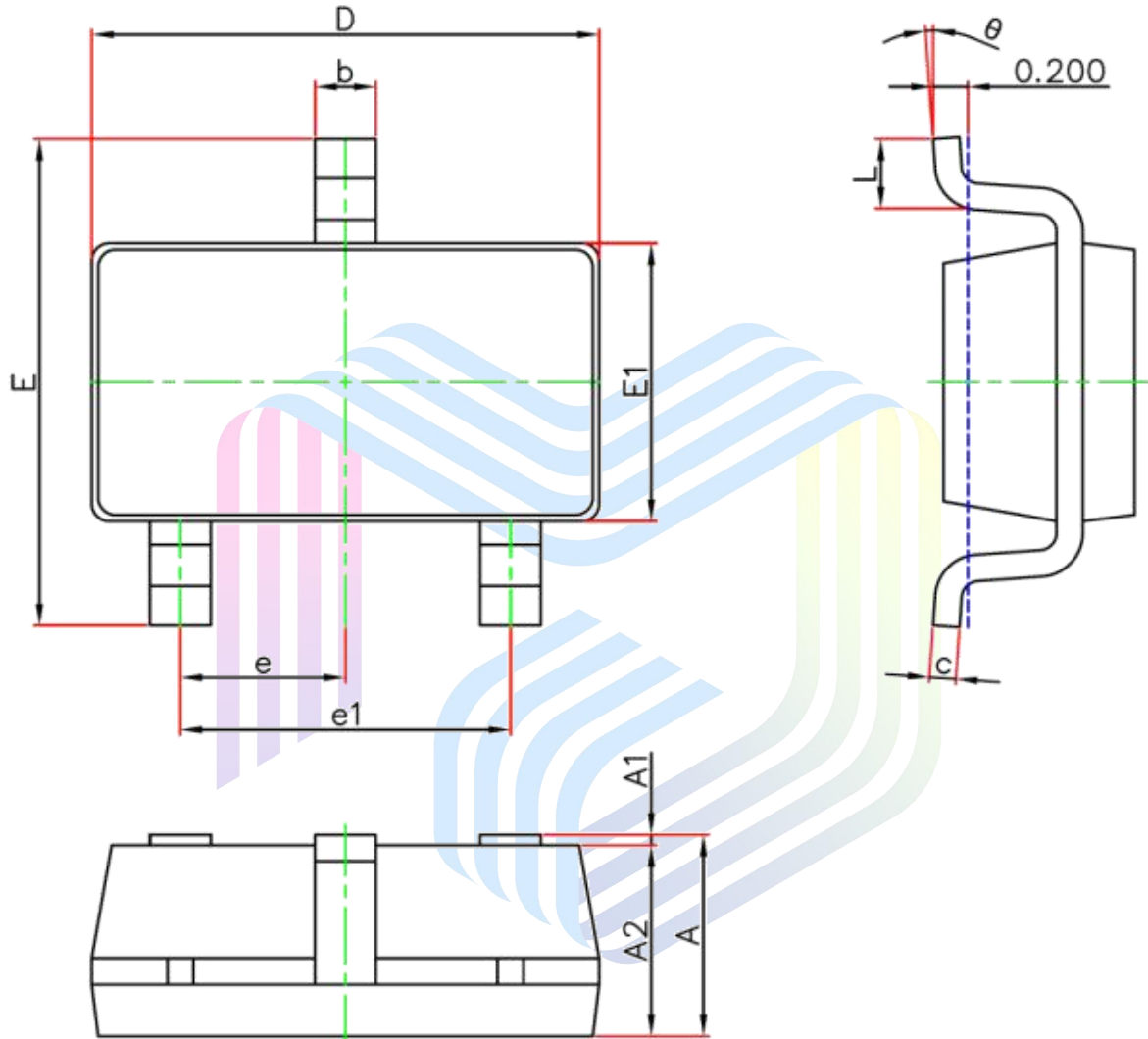
Notes :

- 1.The maximum current rating is limited by package.And device mounted on a large heatsink.
- 2.Pulse Test : Pulse Width  $\leq 10\mu s$ , duty cycle  $\leq 1\%$ .
- 3.Pulse Test : Pulse Width  $\leq 380\mu s$ , duty cycle  $\leq 2\%$ .
- 4.The power dissipation  $P_D$  is limited by  $T_{J(MAX)} = 150^\circ\text{C}$ .And device mounted on a large heatsink
- 5.Device mounted on  $1in^2$  FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25^\circ\text{C}$ .

### Typical Performance Characteristics






**Mechanical Dimensions:**
**SOT-23-3L Package Information**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.050	1.250	0.041	0.049
A1	0	0.150	0.000	0.006
A2	1.050	1.250	0.041	0.049
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	2.650	2.950	0.104	0.116
E1	1.500	1.700	0.059	0.067
e	0.950TYP		0.037TYP	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

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